SAMSUNG ELECTRO-MECHANICS

Ver 201305

Chip Bead For EMI Suppression

CIB/CIM05 Series (1005/ EIA 0402)

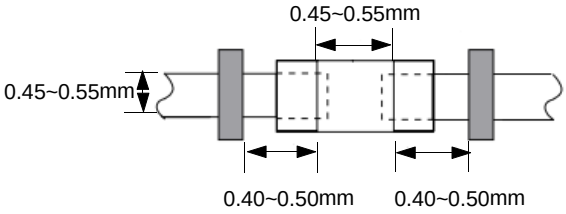
APPLICATION

High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

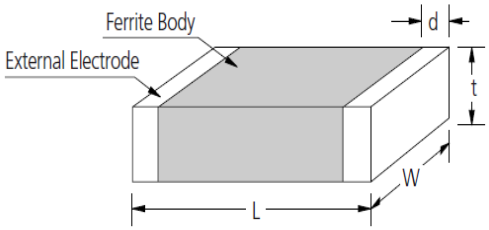
FEATURES

- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.

RECOMMENDED LAND PATTERN



DIMENSION



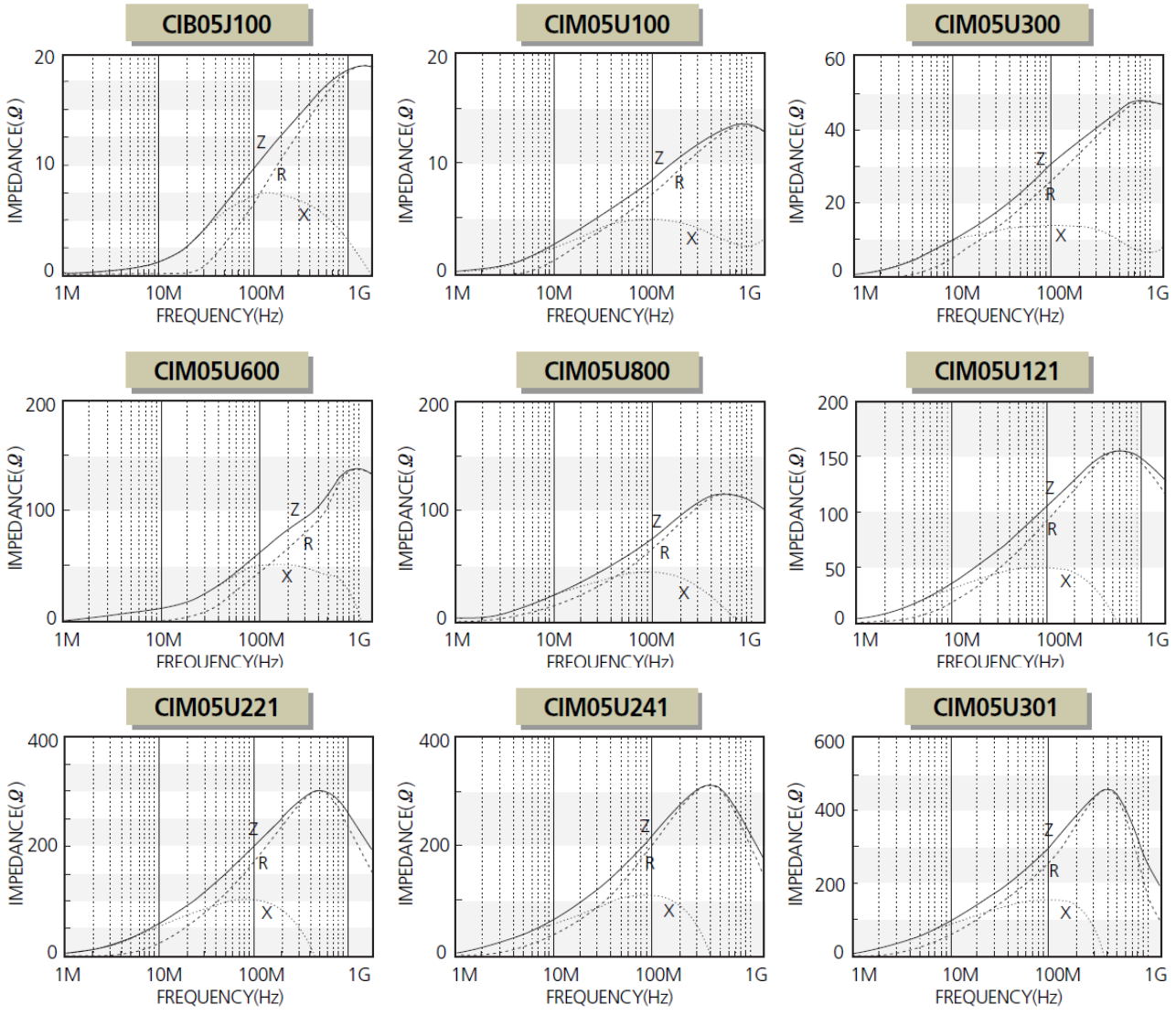
Type	Dimension [mm]			
	L	W	t	d
05	1.0±0.05	0.5±0.05	0.5±0.05	0.25±0.1

DESCRIPTION

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB05J100	0.5±0.05	10	0.05	1200
CIM05U100	0.5±0.05	10	0.05	1200
CIM05U300	0.5±0.05	30	0.10	700
CIM05U600	0.5±0.05	60	0.15	600
CIM05U800	0.5±0.05	80	0.20	600
CIM05U121	0.5±0.05	120	0.25	600
CIM05U221	0.5±0.05	220	0.35	500
CIM05U241	0.5±0.05	240	0.35	400
CIM05U301	0.5±0.05	300	0.45	400
CIM05U471	0.5±0.05	470	0.55	300
CIM05U601	0.5±0.05	600	0.60	300
CIM05U102	0.5±0.05	1000	0.80	300
CIM05J300	0.5±0.05	30	0.20	700
CIM05J600	0.5±0.05	60	0.20	650
CIM05J800	0.5±0.05	80	0.25	600
CIM05J121	0.5±0.05	120	0.25	500
CIM05J221	0.5±0.05	220	0.35	400
CIM05J241	0.5±0.05	240	0.35	400
CIM05J301	0.5±0.05	300	0.45	400
CIM05J471	0.5±0.05	470	0.55	300
CIM05J601	0.5±0.05	600	0.60	300

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIM05J102	0.5±0.05	1000	0.80	250
CIM05J152	0.5±0.05	1500	1.00	250
CIM05J182	0.5±0.05	1800	1.40	200
CIM05N750	0.5±0.05	75	0.35	300
CIM05N121	0.5±0.05	120	0.55	300
CIM05N221	0.5±0.05	220	0.80	200
CIM05F050	0.5±0.05	5	0.08	500
CIM05F100	0.5±0.05	10	0.10	300
CIM05F220	0.5±0.05	22	0.20	300
CIM05F470	0.5±0.05	47	0.35	300
CIM05F750	0.5±0.05	75	0.40	300
CIM05F121	0.5±0.05	120	0.55	300
CIM05F221	0.5±0.05	220	0.80	200
CIM05H800	0.5±0.05	80	0.20	450
CIM05H121	0.5±0.05	120	0.25	400
CIM05H601	0.5±0.05	600	0.80	200

CHARACTERISTIC DATA



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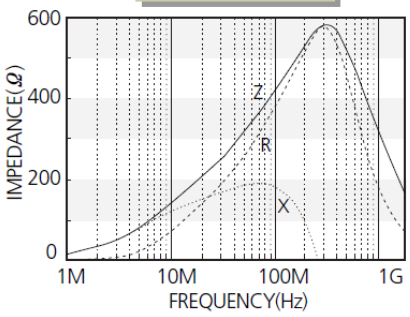

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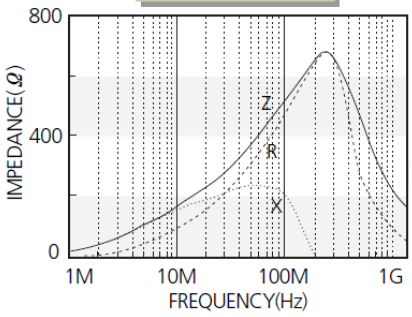

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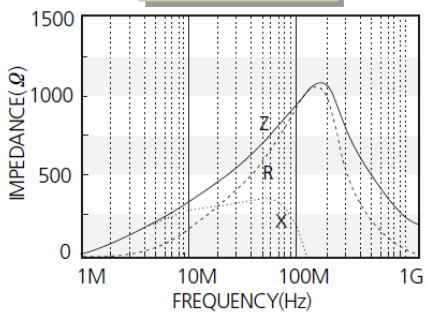

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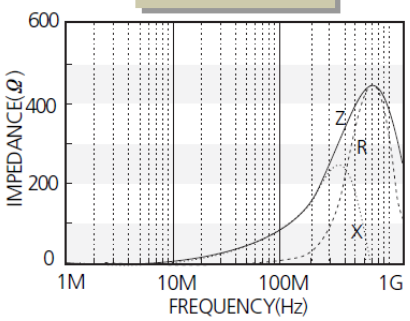

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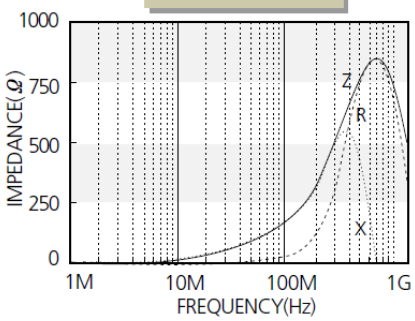

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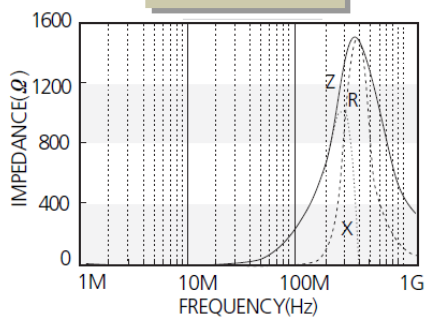

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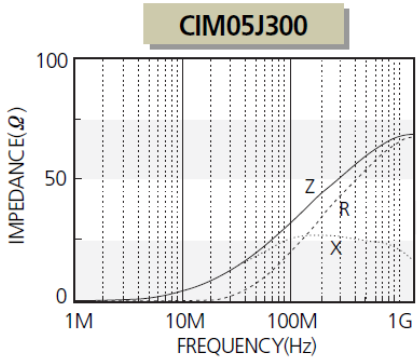

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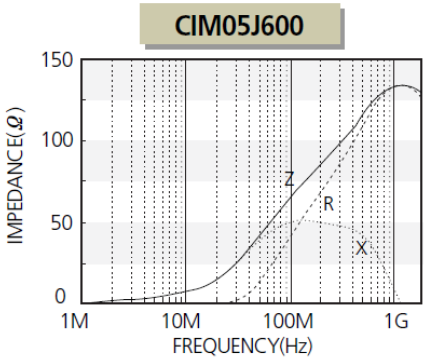

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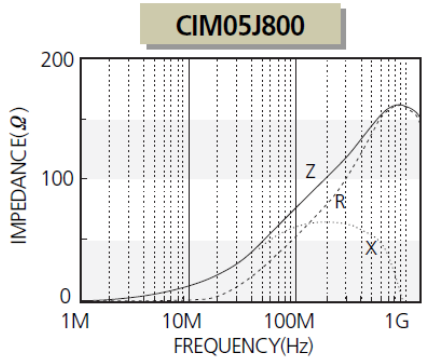

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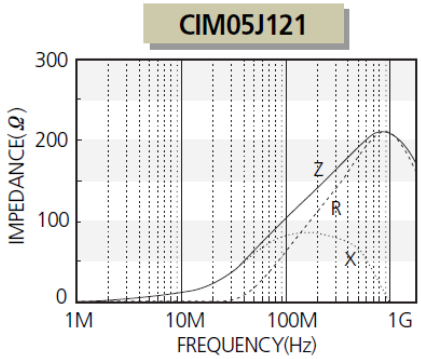

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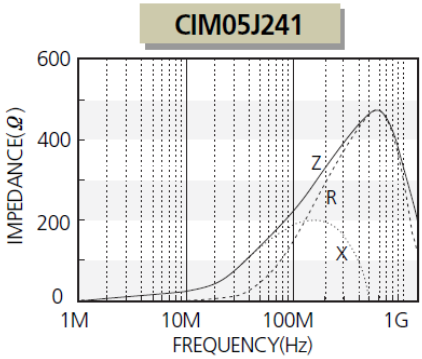

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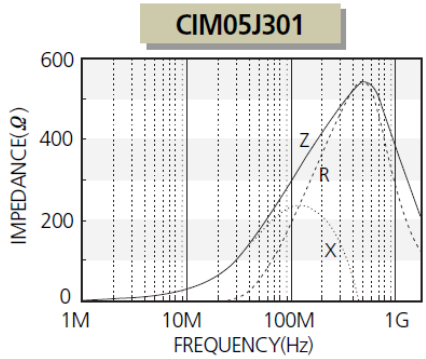

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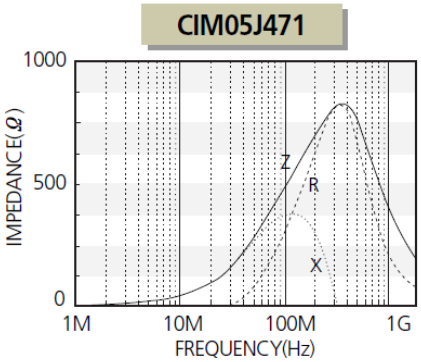

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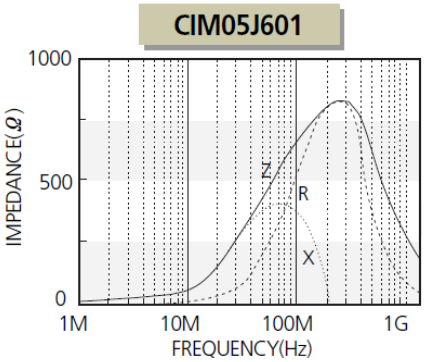

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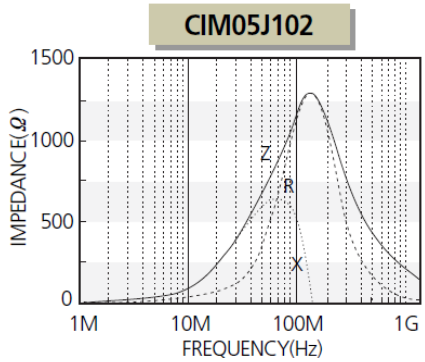

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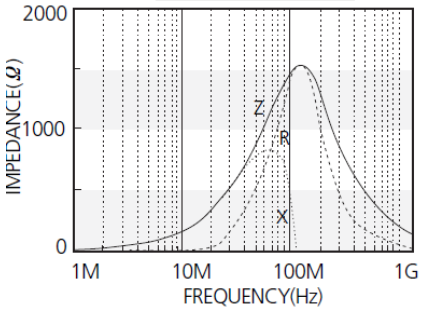

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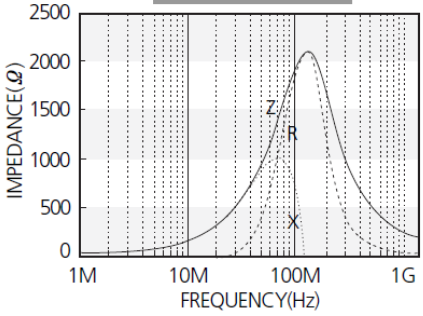

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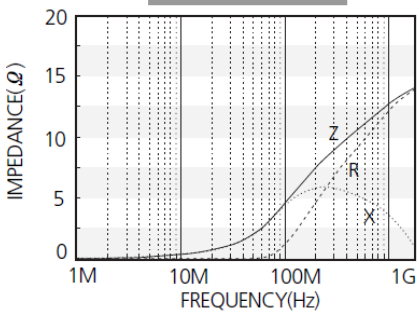

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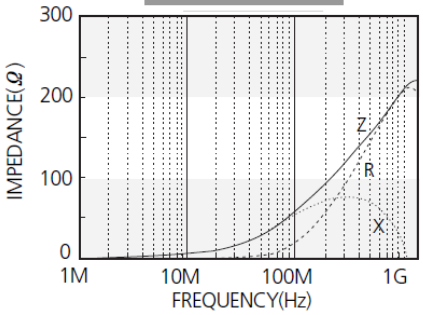

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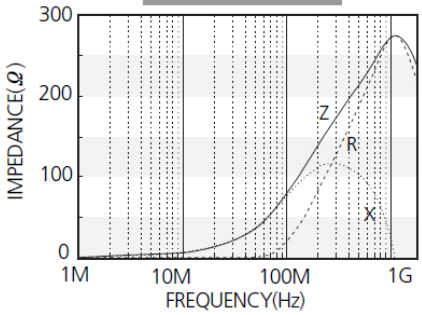

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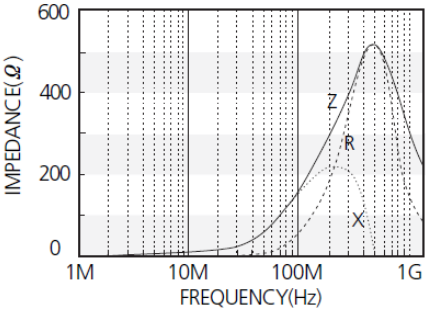

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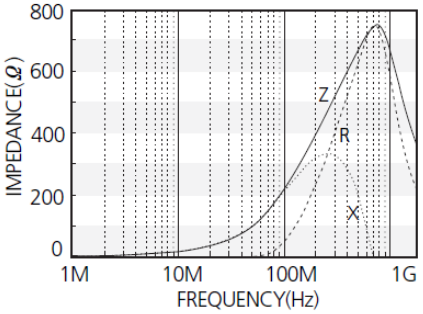

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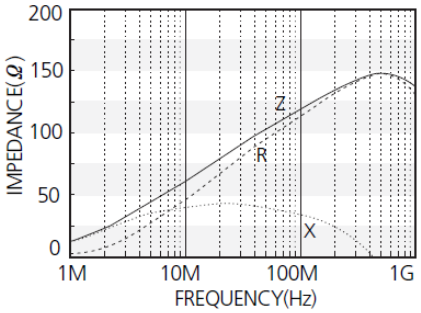

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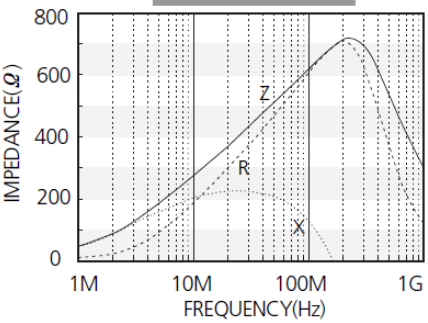


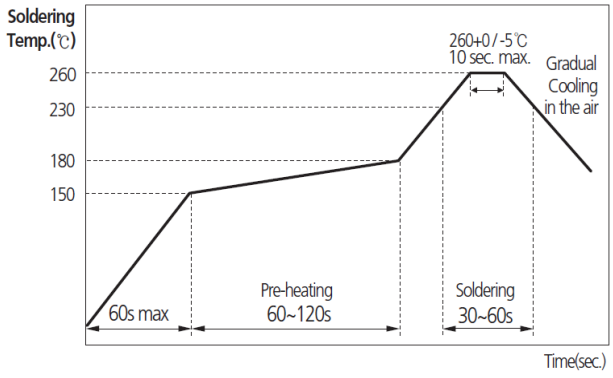
PRODUCT IDENTIFICATION

CI	M	05	U	121	N	C
(1)	(2)	(3)	(4)	(5)	(6)	(7)

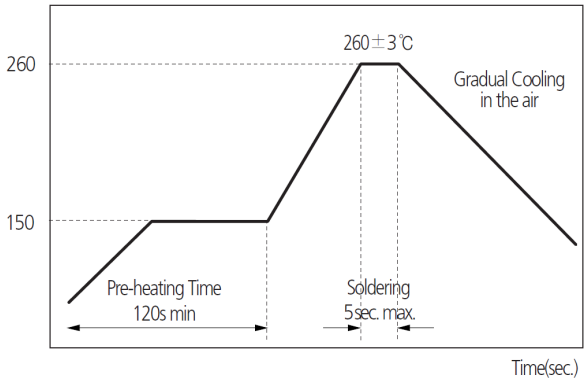
(1) Chip Beads
(2) M: Multi-layer type B:Mono-layer type
(3) Dimension
(4) Material Code
(5) Nominal impedance (100:10Ω, 121:120Ω)
(6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
(7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	10,000